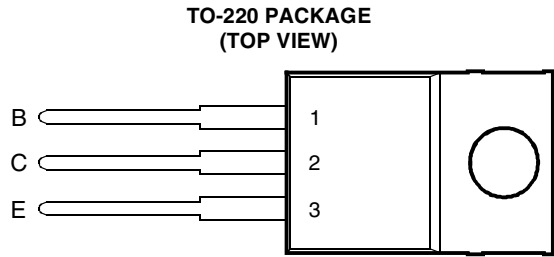




- Designed for Complementary Use with the BD544 Series
- 70 W at 25°C Case Temperature
- 8 A Continuous Collector Current
- 10 A Peak Collector Current
- Customer-Specified Selections Available



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Collector-base voltage ($I_E = 0$)	BD543	V_{CBO}	40	V
	BD543A		60	
	BD543B		80	
	BD543C		100	
Collector-emitter voltage ($I_B = 0$)	BD543	V_{CEO}	40	V
	BD543A		60	
	BD543B		80	
	BD543C		100	
Emitter-base voltage		V_{EBO}	5	V
Continuous collector current		I_C	8	A
Peak collector current (see Note 1)		I_{CM}	10	A
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)		P_{tot}	70	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)		P_{tot}	2	W
Operating free air temperature range		T_A	-65 to +150	°C
Operating junction temperature range		T_j	-65 to +150	°C
Storage temperature range		T_{stg}	-65 to +150	°C
Lead temperature 3.2 mm from case for 10 seconds		T_L	260	°C

NOTES: 1. This value applies for $t_p \leq 0.3$ ms, duty cycle $\leq 10\%$.
2. Derate linearly to 150°C case temperature at the rate of 0.56 W/°C.
3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.

PRODUCT INFORMATION

electrical characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
$V_{(BR)CEO}$ Collector-emitter breakdown voltage	$I_C = 30 \text{ mA}$ (see Note 4)	$I_B = 0$	BD543 BD543A BD543B BD543C	40 60 80 100			V
I_{CES} Collector-emitter cut-off current	$V_{CE} = 40 \text{ V}$ $V_{CE} = 60 \text{ V}$ $V_{CE} = 80 \text{ V}$ $V_{CE} = 100 \text{ V}$	$V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$	BD543 BD543A BD543B BD543C			0.4 0.4 0.4 0.4	mA
I_{CEO} Collector cut-off current	$V_{CE} = 30 \text{ V}$ $V_{CE} = 60 \text{ V}$	$I_B = 0$ $I_B = 0$	BD543/543A BD543B/543C			0.7 0.7	mA
I_{EBO} Emitter cut-off current	$V_{EB} = 5 \text{ V}$	$I_C = 0$				1	mA
h_{FE} Forward current transfer ratio	$V_{CE} = 4 \text{ V}$ $V_{CE} = 4 \text{ V}$ $V_{CE} = 4 \text{ V}$	$I_C = 1 \text{ A}$ $I_C = 3 \text{ A}$ $I_C = 5 \text{ A}$	(see Notes 4 and 5)	60 40 15			
$V_{CE(sat)}$ Collector-emitter saturation voltage	$I_B = 0.3 \text{ A}$ $I_B = 1 \text{ A}$ $I_B = 1.6 \text{ A}$	$I_C = 3 \text{ A}$ $I_C = 5 \text{ A}$ $I_C = 8 \text{ A}$	(see Notes 4 and 5)			0.5 0.5 1	V
V_{BE} Base-emitter voltage	$V_{CE} = 4 \text{ V}$	$I_C = 5 \text{ A}$	(see Notes 4 and 5)			1.4	V
h_{fe} Small signal forward current transfer ratio	$V_{CE} = 10 \text{ V}$	$I_C = 0.5 \text{ A}$	$f = 1 \text{ kHz}$	20			
$ h_{fe} $ Small signal forward current transfer ratio	$V_{CE} = 10 \text{ V}$	$I_C = 0.5 \text{ A}$	$f = 1 \text{ MHz}$	3			

NOTES: 4. These parameters must be measured using pulse techniques, $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

5. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$ Junction to case thermal resistance			1.79	°C/W
$R_{\theta JA}$ Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t_{on} Turn-on time	$I_C = 6 \text{ A}$	$I_{B(on)} = 0.6 \text{ A}$	$I_{B(off)} = -0.6 \text{ A}$		0.6		μs
t_{off} Turn-off time	$V_{BE(off)} = -4 \text{ V}$	$R_L = 5 \Omega$	$t_p = 20 \mu\text{s}$, dc $\leq 2\%$		1		μs

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

TYPICAL CHARACTERISTICS

**TYPICAL DC CURRENT GAIN
VS
COLLECTOR CURRENT**

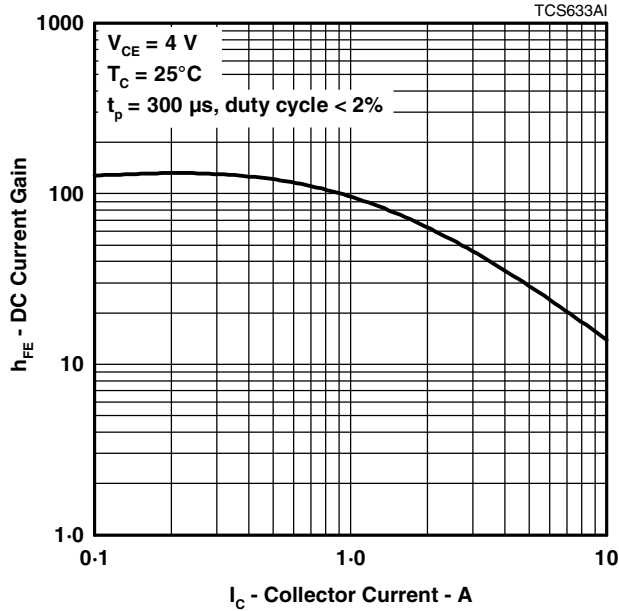


Figure 1.

**COLLECTOR-EMITTER SATURATION VOLTAGE
VS
BASE CURRENT**

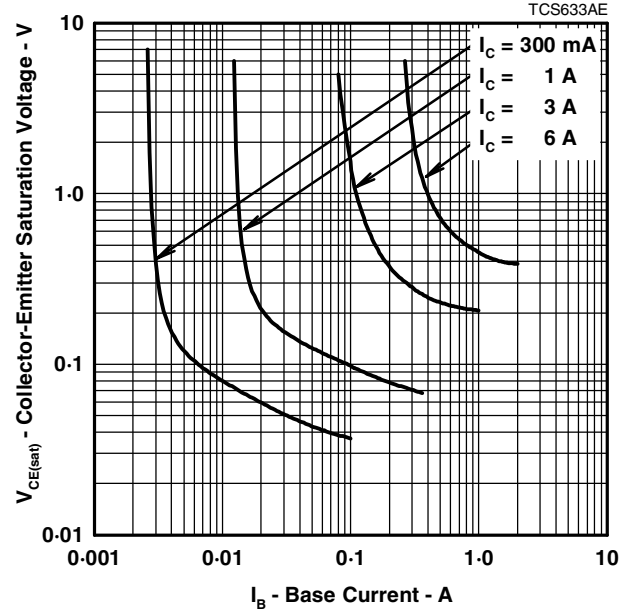


Figure 2.

**BASE-EMITTER VOLTAGE
VS
COLLECTOR CURRENT**

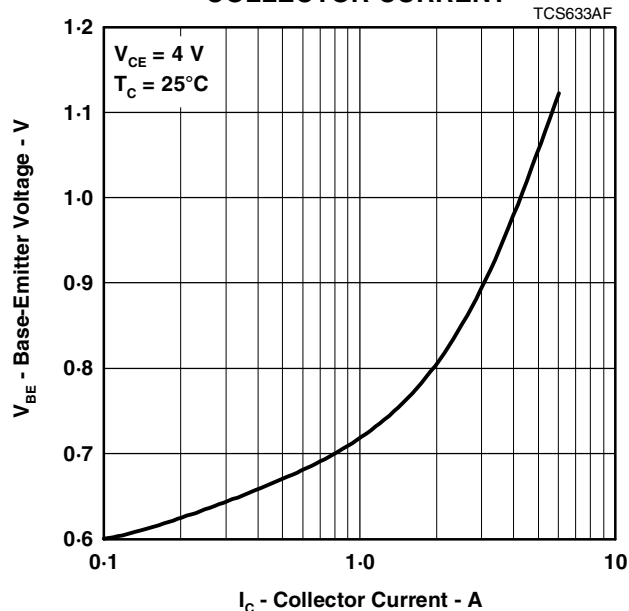


Figure 3.

PRODUCT INFORMATION

MAXIMUM SAFE OPERATING REGIONS

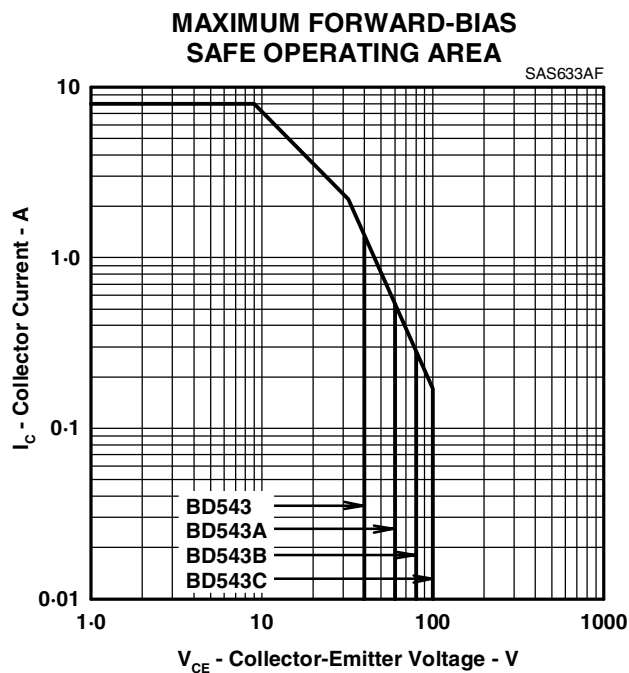


Figure 4.

THERMAL INFORMATION

MAXIMUM POWER DISSIPATION vs CASE TEMPERATURE

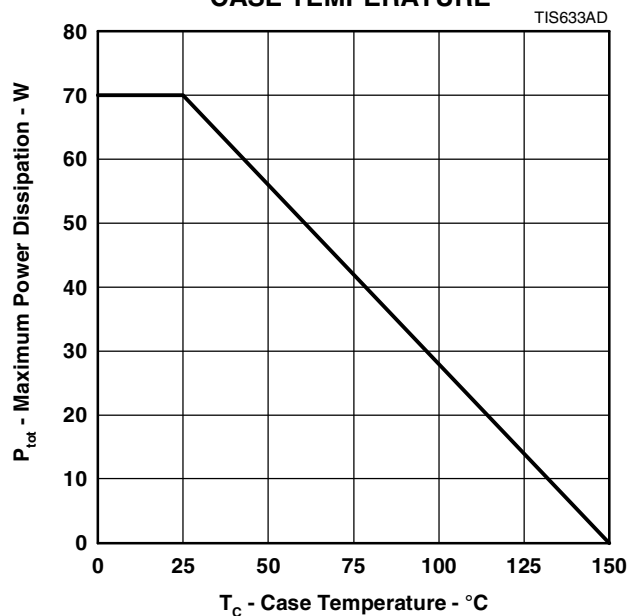


Figure 5.

PRODUCT INFORMATION

JUNE 1973 - REVISED SEPTEMBER 2002
Specifications are subject to change without notice.

TO-220

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.

